



# Investor Presentation

Fall / Winter 2011

# Disclaimer

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which are explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

# Content

- I. Executive Summary
- II. Products and Markets
- III. Growth Opportunities
- IV. Financials
- V. Outlook

# SUSS MicroTec Spotlight

- + SUSS MicroTec: A global leader in semiconductor equipment
- + Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- + We are focused on high growth market segments: Semiconductors, MEMS, LEDs



## Key Data:

- + Bloomberg Symbol: SMH
- + TecDax
- + Share price\*: 7.65 €
- + Market Cap\*: 146 € million
- + Net Cash: 40.1 € million

\* October 31, 2011

# Optimizing Structures – Shaping the Future



## Garching

- + SÜSS MicroTec AG HQ
- + Development and production:
  - Mask Aligner
  - Bond Aligner
- + Core competencies:
  - Exposure
  - Alignment



## Sternenfelds

- + Development and production :
  - Bonder
  - Coater and Developer
  - Photomask Equipment
- + Core competencies :
  - Wet processing
  - Wafer bonding

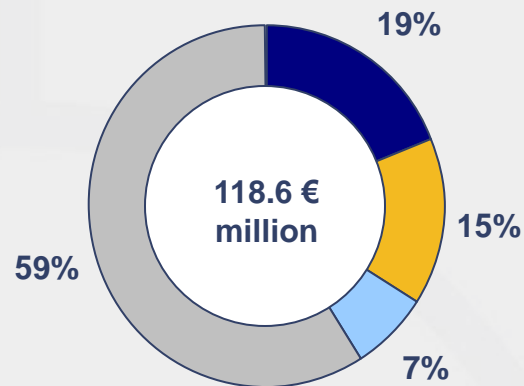
# SUSS MicroTec – A Global Player



# Order Intake and Sales by Region 9M 2011

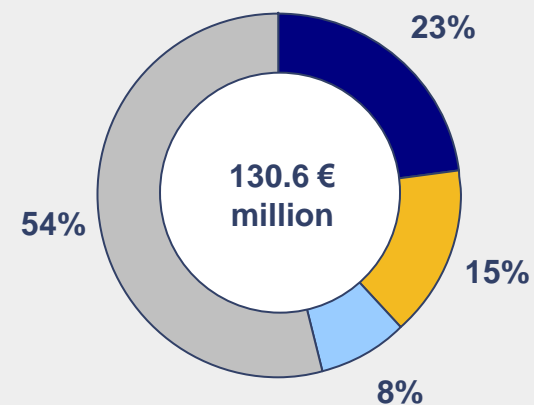
continuing operations

## Order Intake



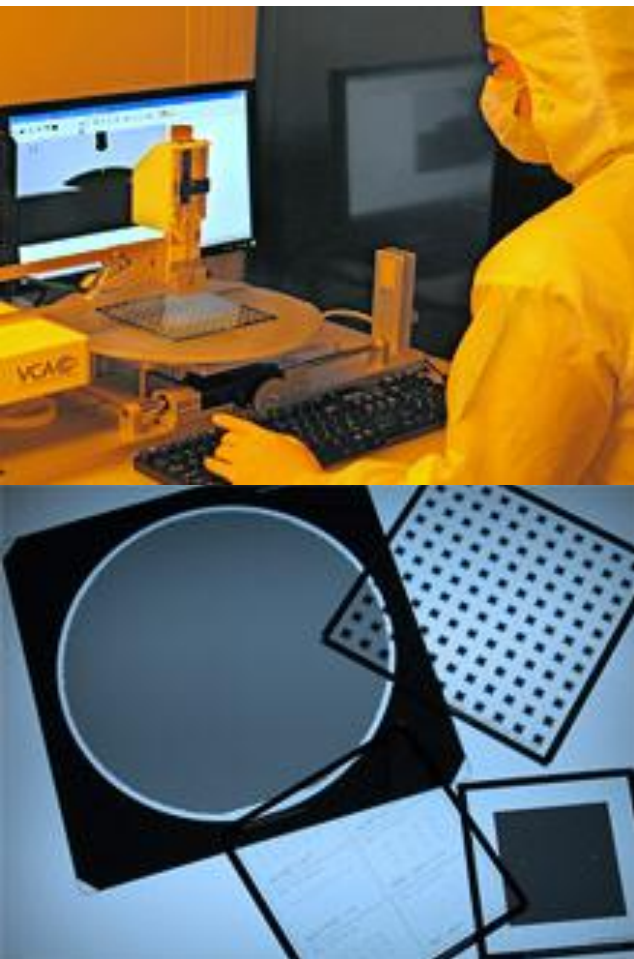
■ Europe	22.0 € million
■ North America	17.4 € million
■ Japan	8.4 € million
■ Rest of Asia	70.7 € million

## Sales



■ Europe	30.0 € million
■ North America	20.0 € million
■ Japan	9.8 € million
■ Rest of Asia	70.8 € million

# Divestment of SUSS Photomask Precision Inc.



- + Sale of SUSS MicroTec Precision Photomask Inc. to Compugraphics Inc., Los Gatos, CA
- + Sale of all assets
- + Limited synergies with core business units
- + Focus on profitable and high growth business areas
- + Supports the expansion of the SUSS MicroTec Photo Mask Equipment
- + Eliminating competitive overlap with prospective customers

## The Purchaser:

- + Compugraphics is a globally acting mask manufacturer with mask shops in the US, UK and Germany



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# SUSS MicroTec In The Value Chain

- + SUSS MicroTec is a key player in providing state-of-the-art semiconductor manufacturing equipment

- + With industry and R&D partners we develop highly innovative systems addressing the fundamental challenges of semiconductor manufacturing



- + With SUSS MicroTec's manufacturing solutions the components are built out of which cell phones, PCs, tablet computers, TV sets etc. are made

# Segments and Products

## Segments

**Photomask  
Equipment**

**Lithography**

**Substrate Bonder**

## Products



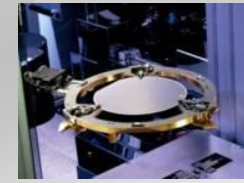
**Mask Track**



**Mask Aligner**



**Coater/  
Developer**



**Wafer Bonder**

## Process Steps

**Frontend**

**Backend**



**Photomask Cleaning**



**Alignment  
Exposure  
Nano Imprinting**



**Coating  
Developing**



**Bond Alignment  
Permanent Bonding  
Temporary Bonding**

## Key figures 9M 2011

**Sales: 25.8 € million  
EBIT: 4.4 € million**

**Sales: 84.4 € million  
EBIT: 20.0 € million**

**Sales: 14.8 € million  
EBIT: -7.7 € million**

# Products and Markets

## Products



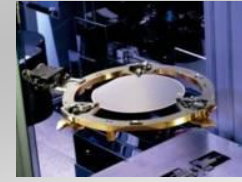
Mask Track



Mask Aligner



Coater/  
Developer



Wafer Bonder

## Process Steps

Frontend



Photomask  
Cleaning

Backend



Alignment  
Exposure  
Nano Imprinting



Coating  
Developing



Bond Alignment  
Permanent Bonding  
Temporary Bonding

## Markets

Mask Making

Advanced Packaging

3D - Integration

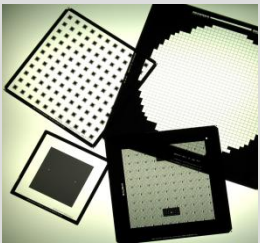
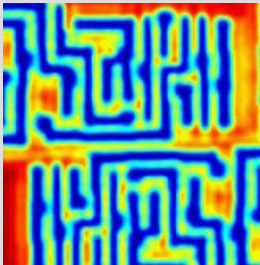
MEMS

LED

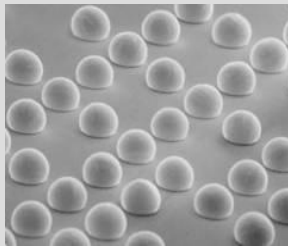
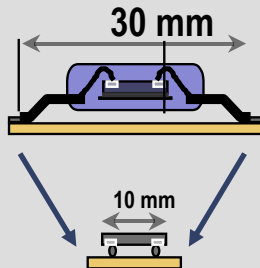
# Key Markets

## Semiconductor

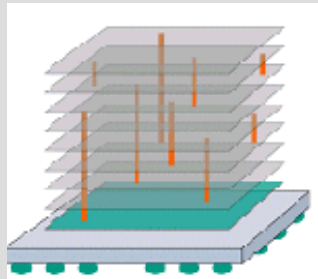
### Mask Making Photomask Cleaning



### Advanced Packaging Micro-Bumping



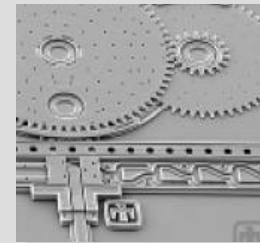
### 3D Integration/ Stacking



## Sensors

### MEMS

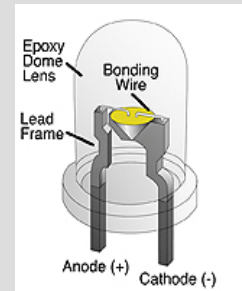
Computing, Automotive,  
Medical Applications ...



## Lighting

### LED

General Lighting,  
HB and UHB LED



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# Mega Trends driving the Industry

- + Global mega trends drive the micro electronics industry and create long term opportunities
  - **Digital Lifestyle**
  - **E-Mobility**
  - **Energy efficiency**
- + Micro chips, MEMS und LEDs are the building blocks for the technological product advancement
- + SUSS MicroTec's focus is to offer development and manufacturing solutions for these components in markets that have a sustainable long term growth perspective



3D Integration

Digital lifestyle



Pressure Sensors

MEMS

E-mobility



LED/Optoelectronics

Energy efficiency

# Enabling Semiconductor Trends

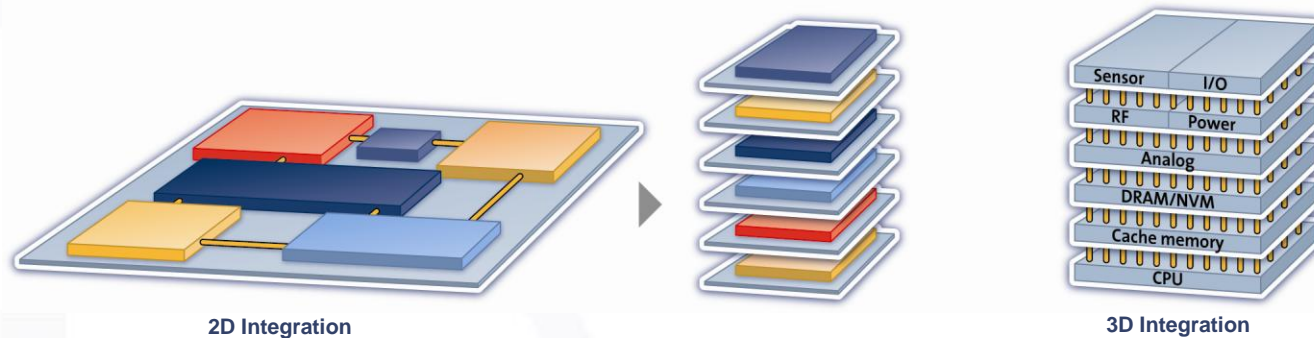
- + The further increase in complexity and performance of future semiconductor device generations demands the continuous progress in scaling of these devices
- + SUSS MicroTec's equipment and process solutions enable the 2-dimensional reduction of feature sizes ("Moore's Law") as well as the 3-dimensional stacking of integrated circuits ("More than Moore")





# 2-D vs. 3-D Scaling

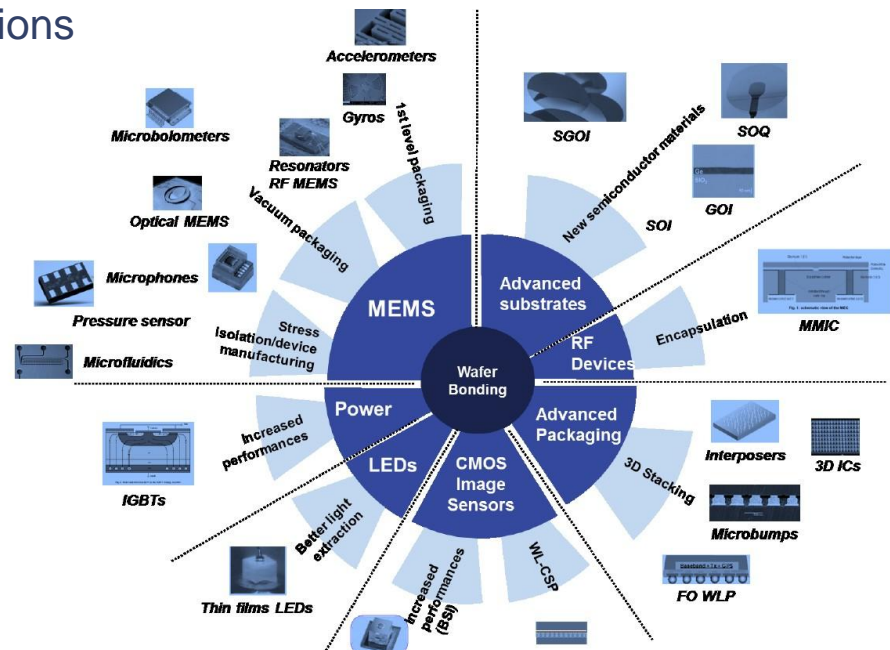
- + Technical challenges and limitations make it increasingly more expensive to pursue the shrink roadmap of integrated circuits
- + While alternatives like 3D integration promise greater space efficiency, lower power consumption and a significant increase in performance they will not replace shrinking



- + For the years to come shrinking and stacking technologies will coexist, each having it's unique set of challenges
- + SUSS MicroTec is one of the few companies offering HVM equipment and process solutions for 2-dimensional and 3-dimensional scaling

# Growth Opportunities

- + The company's long term growth perspective derives from the double digit growth rates of the target markets 3D Integration, Advanced Packaging, LED and MEMS
- + SUSS MicroTec is one of the leading suppliers for wafer bonders in the semiconductor industry offering a broad portfolio of permanent and temporary bonding equipment and process solutions
- + The wafer bonder equipment market is estimated to grow rapidly to a size of larger 500 million \$ within the next few years
- + SUSS MicroTec targets a market share of 30%+ which is in line with the current market position



Source: Yole Développement

# Overview on Temporary (De-Bonding): Traditional vs. New Processes

## New Trend:

*Mechanical Room Temperature Release / Release Layer Approaches*

 **ThinMaterials**

Material made by **WACKER**



*SUSS XBC300*

**brewer science**

ZoneBOND™

## Traditional Methods:

*Thermal Slide*

**brewer science**

WaferBOND™

*Laser Release*

**3M**

Wafer Support System

**DU PONT**

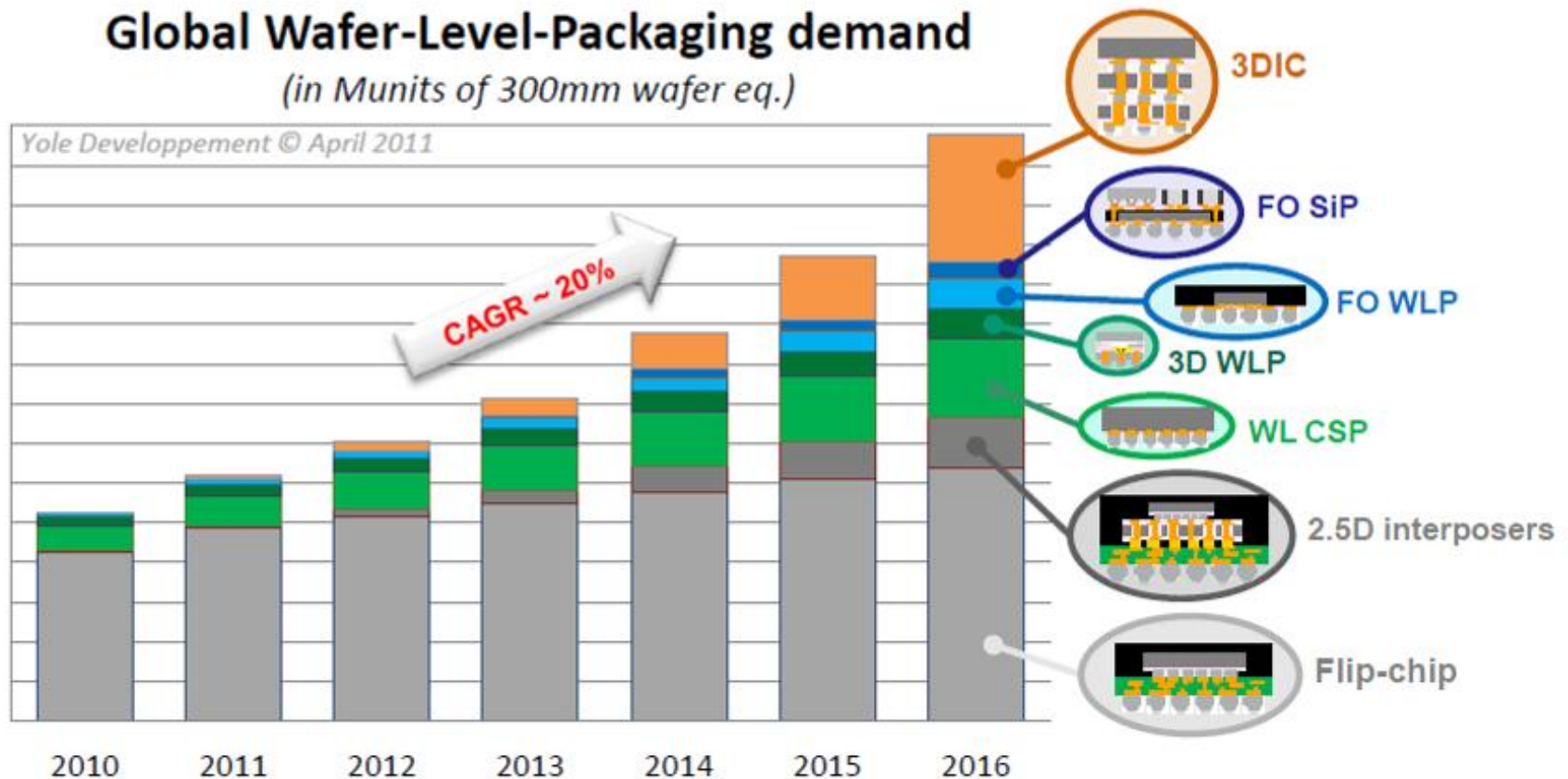
*The miracles of science™*

HD-3007

# Market Forecasts I

## Global Wafer-Level-Packaging demand (in Munits of 300mm wafer eq.)

Yole Developpement © April 2011

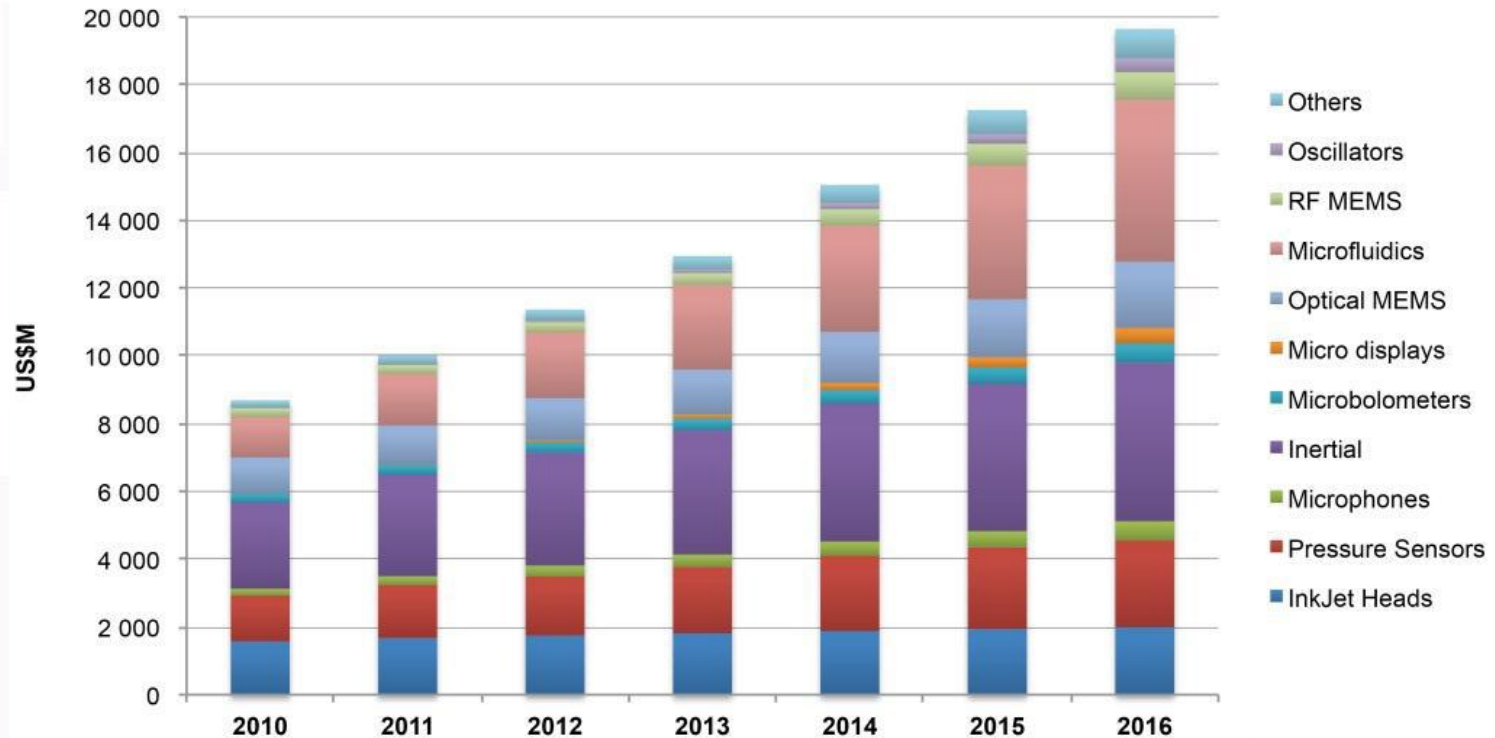


Source: Yole Developpement

# Market Forecasts II

## 2010-2016 MEMS markets forecast (in US\$M)

(Source : Status of the MEMS Industry Report, 2011)



© September 2011

Source: Yole Développement



# Sternenfels – Site for volume manufacturing

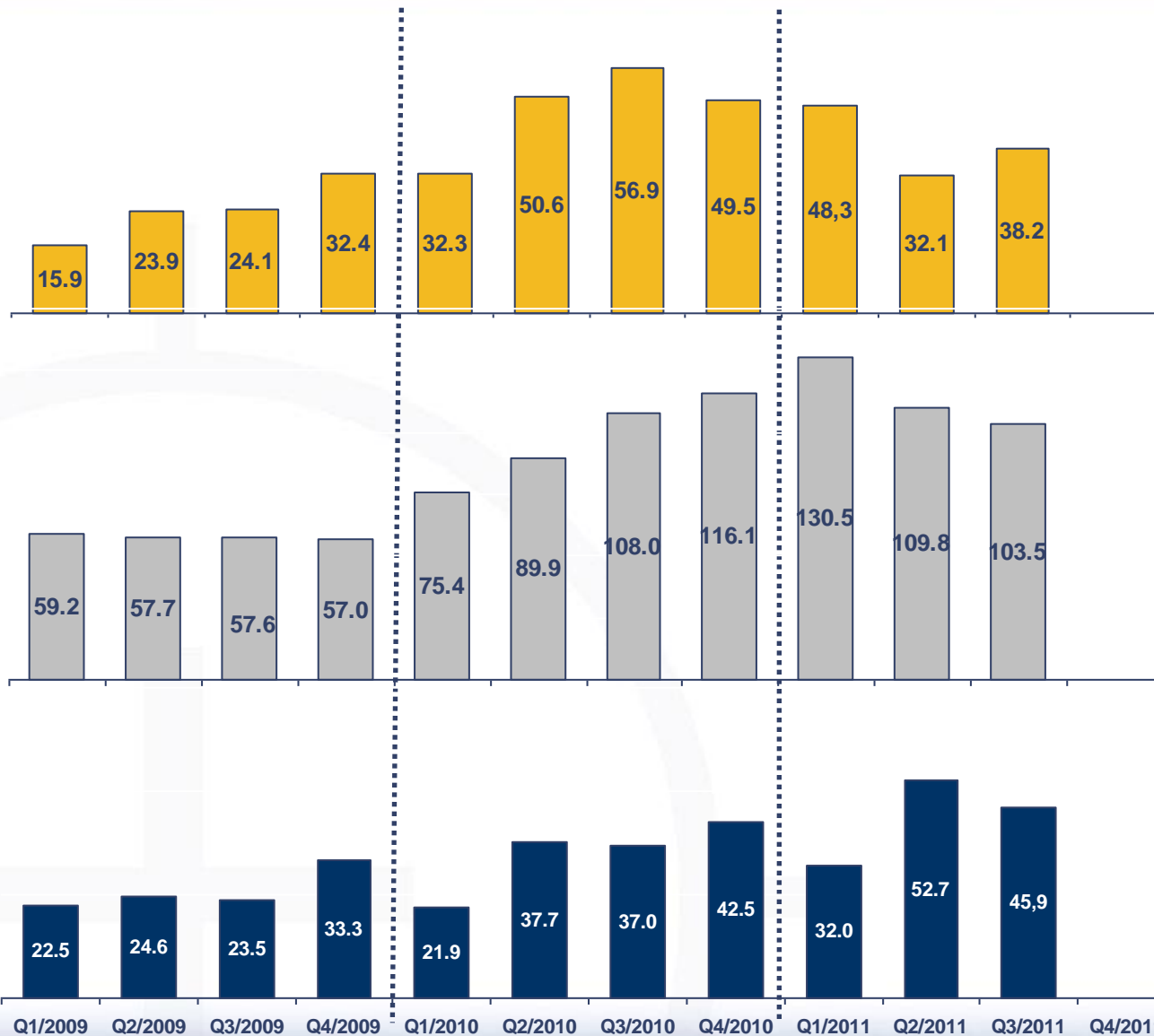
- + Three product lines under one roof
  - Photomask Equipment - Coater / Developer - Bonder
- + Modern production facility (15,000 m<sup>2</sup>) with two large clean rooms supporting future business expansion



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# 33 Months Business Development



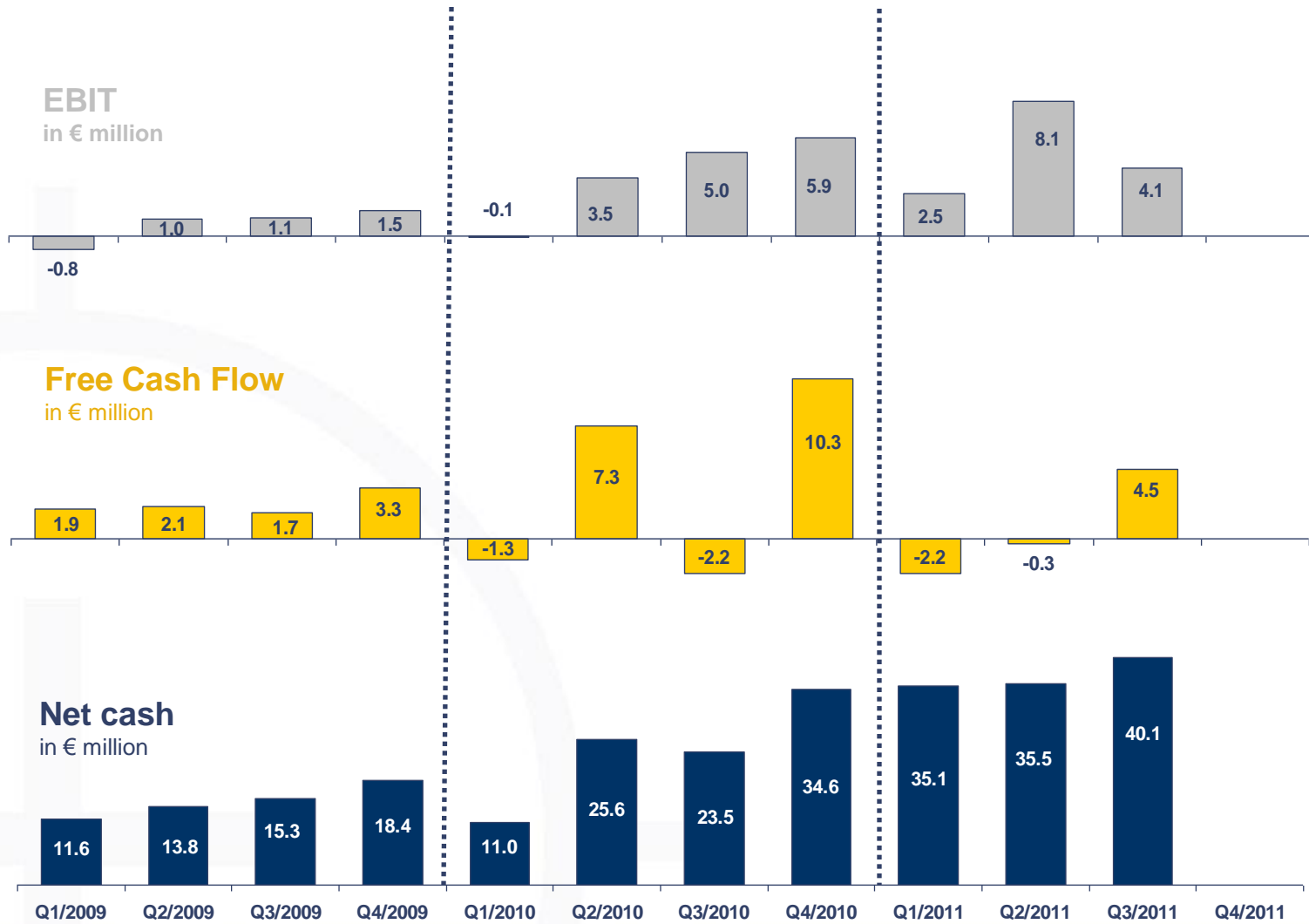
**Order Entry**  
in € million

**Order Backlog**  
in € million

**Sales**  
in € million



# EBIT, Free Cash Flow and Net Cash Development



# Key Financials continuing operations

in € million	Q3 2011	Q3 2010	in %	9M 2011	9M 2010	in %
<b>Order Intake</b>	38,2	56,9	-33%	118,6	139,8	-15%
<b>Order Backlog (09/30)</b>	--	--	--	103,5	108,0	-4%
<b>Revenue</b>	45,9	37,0	+24%	130,6	96,6	+35%
<b>EBIT</b>	4,1	5,0	-18%	14,7	8,4	+75%
<i>EBIT in % of Sales</i>	8,9%	13,5%	-4,6 %-Pkt.	11,3%	8,7%	+2,6 %-Pkt.
<b>Earnings after tax</b>	2,9	2,5	+16%	11,2	3,6	+211%
<b>EPS in € (basic)</b>	0,15	0,13	+15%	0,59	0,19	+211%
<b>Free Cash Flow*</b>	4,5	-2,2	>+250%	2,0	3,8	-47,4%
<b>Net Cash**</b>	--	--	--	40,1	23,5	+70,6%
<b>Employees (09/30)</b>	--	--	--	637	587	+9%

\* Before consideration of purchase or sale of available-for-sale securities and before consideration of extraordinary items from purchase or sale of subsidiaries

\*\* incl. interest-bearing securities

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## Guidance

- + FY 2011e:**
  - Sales of more than 170 € million
  - EBIT-margin 10% – 15%
- + Q4 2011e:**
  - Order Intake € 30 – 40 million
  - Sales of approx. 40 – 45 € million

# Investment case

- + Strong competitive positioning: first or second in the target markets
- + Expansion of the solid financial situation and increasing profitability
- + Strong fundamental growth in target markets
- + Significant mid term revenue opportunity
- + Evolve to a leading company in the semiconductor backend, enabling 3D integration while supporting “Moore’s Law” as well as “More than Moore”
- + Participate in the consolidation of the backend

# Investor Relations Information

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## Contact

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## Financial Calendar 2011/2012

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Nine-month Report 2011	November 8
TMT Conference Morgan Stanley, Barcelona	November 16
German Equity Forum Fall 2011	November 21 - 23
Annual Report 2011	March 30
Quarterly Report 2012	May 8
Shareholders' Meeting, Haus der Bayerischen Wirtschaft, Munich	June 20
Interim Report 2012	August 7
Nine-month Report 2012	November 8